



NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.

2. ALL DIMENSIONS ARE IN MILLIMETERS.

3. DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM

4. PRIMARY DATUM AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

5. BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

6. EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

7. JEDEC REFERENCE: JEP95 DR4.5

	Symbol	Common Dimensions		
		MIN.	NOM.	MAX.
Package:		LFBGA		
Body Size:	X Y	E D	8.000 8.000	BSC BSC
Ball Pitch:	e	0.500		
Total Thickness:	A	1.186	1.262	1.338
Mold Cap Thickness:	A6	0.700		Ref.
Substrate Thickness:	A5	0.352		Ref.
Ball Diameter:		0.300		
Stand Off:	A1	0.160	0.210	0.260
Ball Width:	b	0.270	0.320	0.370
Package Edge Tolerance:	aaa	0.150		
Mold Parallelism:	ccc	0.200		
Coplanarity:	ddd	0.080		
Ball Offset (Package):	eee	0.150		
Ball Offset (Ball):	fff	0.050		
Ball Count:	n	132		
Edge Ball Center to Center:	X Y	E1 D1	6.500 6.500	

Title: Package Outline Drawing

Pkg Type: CABGA

Document No:

Product Family: LFMXO4

Pin Count: 132

POD-250075

Product Name: LFMXO4-010/015/025/050-BSG132

Pkg Size: 8X8 mm

Rev: A

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